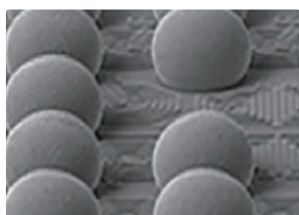




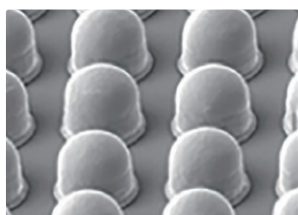
3D/2D/SDの同時測定を
高速・高精度に実現
High-Speed and High-Sensitivity
Fully Automated 3D/2D/SD

金バンプ3D検査に最適
Best Solution for Gold Bump inspection

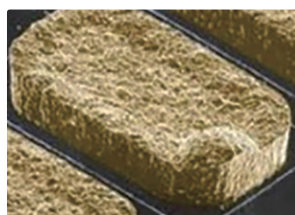
AIシステムによる効率の向上
Improve efficiency with AI system



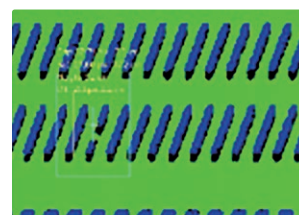
■ Solder bump



■ Cu pillar

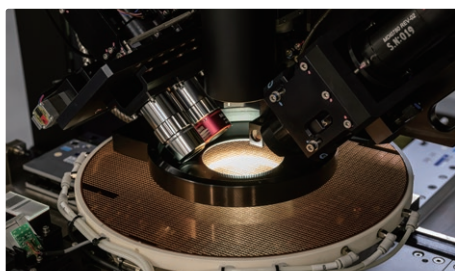


■ Gold bump

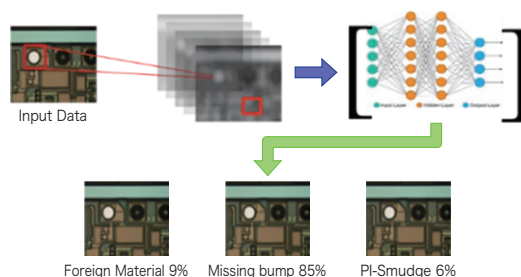


■ Inclined bump

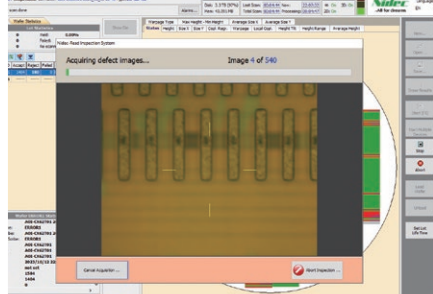
Top class 3D inspection speed



Automatic defect classification

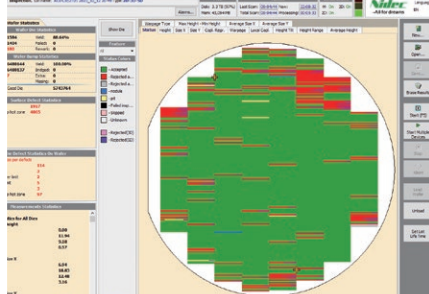


High Accuracy



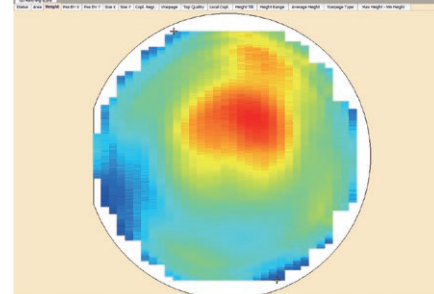
2D/3D測定精度が大きく向上
Height Accuracy(mean bias): 0.17μm*

High Speed



超高速検査を実現
Throughput: 24sec/wafer(2D@12inch)*

High Performance



レビュー(欠陥)画像取得速度が飛躍的に向上
Review Image Capture Speed: 5 fps*

* 当社標準ウエハによる測定結果